

## Single Phase Full Controlled Bridges with freewheeling diode

**PSCT 85**

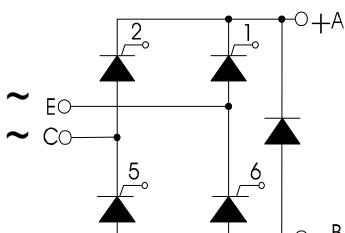
**I<sub>dAV</sub>**  
**V<sub>RRM</sub>**

**= 82 A**  
**= 400-1600 V**

Preliminary Data Sheet

V <sub>RSM</sub>	V <sub>RRM</sub>	Type
V <sub>DSM</sub>	V <sub>DRM</sub>	
500	400	PSCT 85/04
900	800	PSCT 85/08
1300	1200	PSCT 85/12
1500	1400	PSCT 85/14
*1700	*1600	PSCT 85/16

\* Delivery on request



Symbol	Test Conditions		Maximum Ratings	
I <sub>dAV</sub>	T <sub>C</sub> = 85 °C	per module	82	A
I <sub>TSM</sub>	T <sub>VJ</sub> = 45°C	t = 10 ms	(50 Hz), sine	1150 A
	V <sub>R</sub> = 0	t = 8.3 ms	(60 Hz), sine	1230 A
	T <sub>VJ</sub> = T <sub>VJM</sub>	t = 10 ms	(50 Hz), sine	1000 A
	V <sub>R</sub> = 0	t = 8.3 ms	(60 Hz), sine	1070 A
$\int i^2 dt$	T <sub>VJ</sub> = 45°C	t = 10 ms	(50 Hz), sine	6600 A <sup>2</sup> s
	V <sub>R</sub> = 0	t = 8.3 ms	(60 Hz), sine	6280 A <sup>2</sup> s
	T <sub>VJ</sub> = T <sub>VJM</sub>	t = 10 ms	(50 Hz), sine	5000 A <sup>2</sup> s
	V <sub>R</sub> = 0	t = 8.3 ms	(60 Hz), sine	4750 A <sup>2</sup> s
(di/dt) <sub>cr</sub>	T <sub>VJ</sub> = T <sub>JVM</sub>	repetitive, I <sub>T</sub> = 50 A	150	A/μs
	f = 400Hz, t <sub>p</sub> = 200μs			
	V <sub>D</sub> = 2/3 V <sub>DRM</sub>			
	I <sub>G</sub> = 0.3 A	non repetitive, I <sub>T</sub> = 1/3 · I <sub>dAV</sub>	500	A/μs
	diG/dt = 0.3 A/μs			
(dv/dt) <sub>cr</sub>	T <sub>VJ</sub> = T <sub>VJM</sub>	V <sub>DR</sub> = 2/3 V <sub>DRM</sub>	1000	V/μs
	R <sub>GK</sub> = ∞, method 1 (linear voltage rise)			
P <sub>GM</sub>	T <sub>VJ</sub> = T <sub>VJM</sub>	t <sub>p</sub> = 30μs	≤ 10	W
	I <sub>T</sub> = I <sub>TAVM</sub>	t <sub>p</sub> = 500μs	≤ 5	W
P <sub>GAVM</sub>			0.5	W
V <sub>RGM</sub>			10	V
T <sub>VJ</sub>			-40 ... + 125	°C
T <sub>VJM</sub>			125	°C
T <sub>stg</sub>			-40 ... + 125	°C
V <sub>ISOL</sub>	50/60 HZ, RMS	t = 1 min	2500	V ~
	I <sub>ISOL</sub> ≤ 1 mA	t = 1 s	3000	V ~
M <sub>d</sub>	Mounting torque	(M6)	5	Nm
	Terminal connection torque	(M6)	5	Nm
Weight	typ.		270	g

### Features

- Package with screw terminals
- Isolation voltage 3000 V~
- Planar glasspassivated chips
- Low forward voltage drop
- UL released, E 148688

### Applications

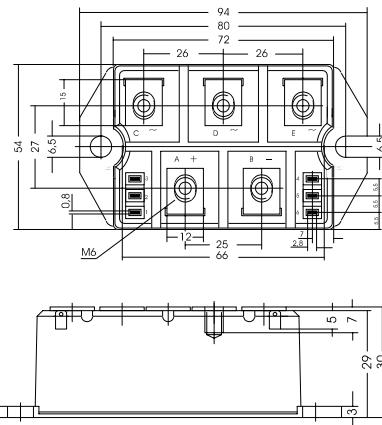
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Motor control
- Power converter

### Advantages

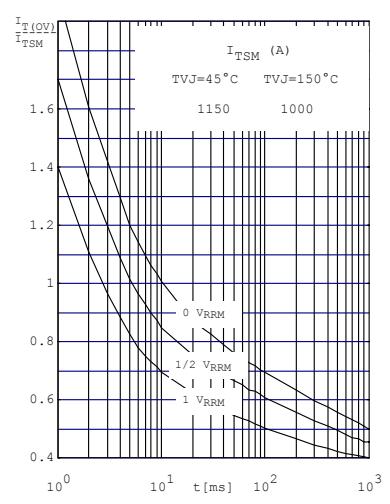
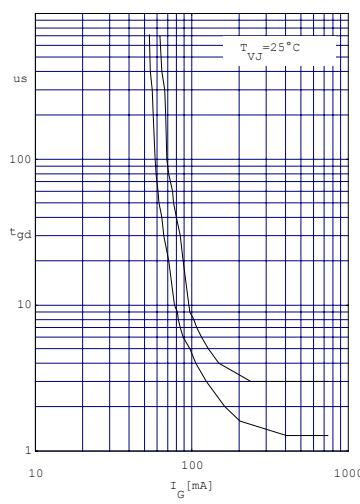
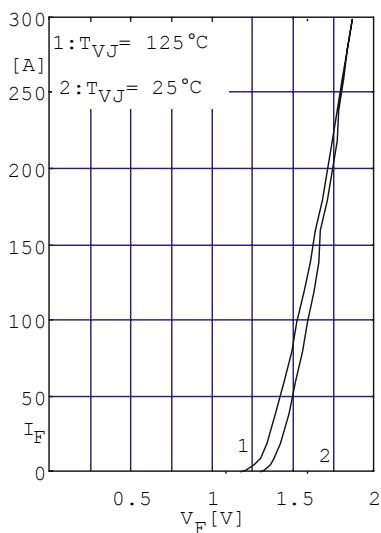
- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling capability
- High power density

### Package, style and outline

Dimensions in mm (1mm = 0.0394")



Symbol	Test Conditions		Characteristic Value		
$I_D, I_R$	$T_{VJ} = T_{VJM}$ , $V_R = V_{RRM}$ , $V_D = V_{DRM}$		$\leq$	5	mA
$V_T$	$I_T = 200A$ , $T_{VJ} = 25^\circ C$		$\leq$	1.75	V
$V_{TO}$	For power-loss calculations only ( $T_{VJ} = T_{VJM}$ )			0.85	V
$r_T$				6	$m\Omega$
$V_{GT}$	$V_D = 6V$	$T_{VJ} = 25^\circ C$	$\leq$	1.5	V
		$T_{VJ} = -40^\circ C$	$\leq$	1.6	V
$I_{GT}$	$V_D = 6V$	$T_{VJ} = 25^\circ C$	$\leq$	100	mA
		$T_{VJ} = -40^\circ C$	$\leq$	200	mA
$V_{GD}$	$T_{VJ} = T_{VJM}$	$V_D = 2/3 V_{DRM}$	$\leq$	0.2	V
$I_{GD}$	$T_{VJ} = T_{VJM}$	$V_D = 2/3 V_{DRM}$	$\leq$	5	mA
$I_L$	$T_{VJ} = 25^\circ C$ , $t_P = 30\mu s$		$\leq$	450	mA
	$I_G = 0.3A$ , $dI_G/dt = 0.3A/\mu s$				
$I_H$	$T_{VJ} = 25^\circ C$ , $V_D = 6V$ , $R_{GK} = \infty$		$\leq$	200	mA
$t_{gd}$	$T_{VJ} = 25^\circ C$ , $V_D = 1/2 V_{DRM}$		$\leq$	2	$\mu s$
	$I_G = 0.3A$ , $dI_G/dt = 0.3A/\mu s$				
$t_q$	$T_{VJ} = T_{VJM}$ , $I_T = 20A$ , $t_P = 200\mu s$ , $V_R = 100V$			150	$\mu s$
	$-di/dt = 10A/\mu s$ , $dv/dt = 15V/\mu s$ , $V_D = 2/3 V_{DRM}$				
$R_{thJC}$	per thyristor; sine 180°el			0.65	K/W
	per module			0.13	K/W
$R_{thJK}$	per thyristor; sine 180° el			0.8	K/W
	per module			0.16	K/W
$d_s$	Creeping distance on surface			10.0	mm
$d_A$	Creeping distance in air			9.4	mm
$a$	Max. allowable acceleration			50	$m/s^2$



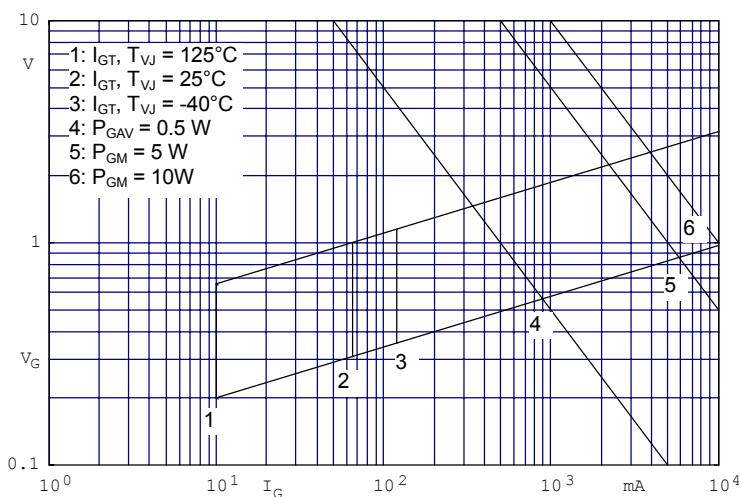


Fig.4 Gate trigger characteristic

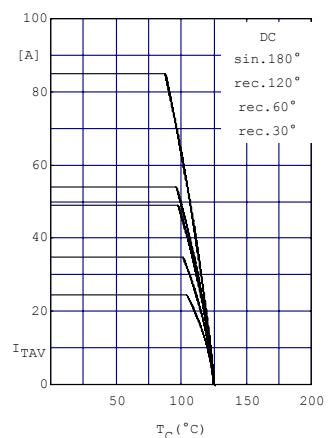


Fig.5 Maximum forward current at case temperature

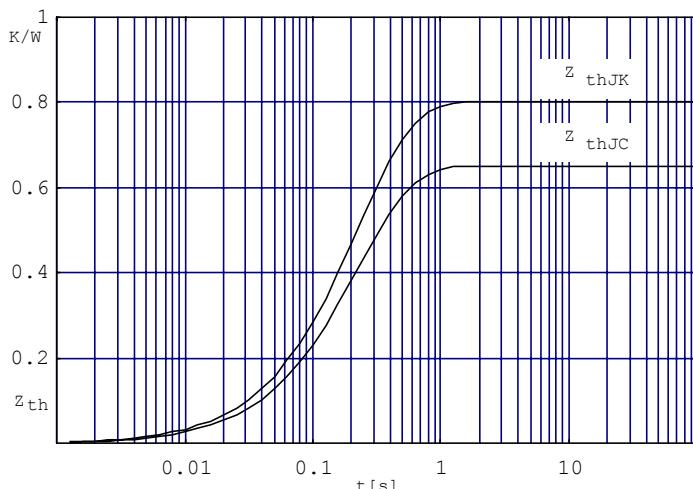


Fig.6 Transient thermal impedance per thyristor or diode (calculated)

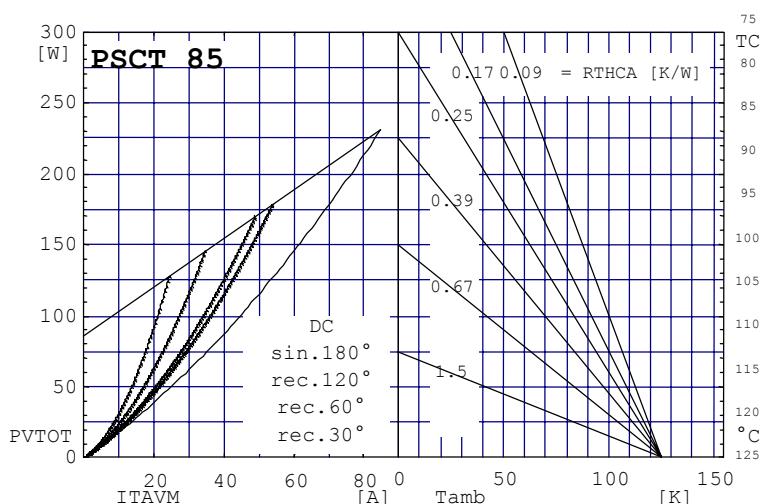


Fig. 7 Power dissipation vs. direct output current and ambient temperature